

|   | Type | L # | Hits   | Search Text                             | DBs                    |
|---|------|-----|--------|---|------------------------|
| 1 | IS&R | L1  | 1      | ("6004405").PN.                         | USPAT                  |
| 2 | BRS  | L2  | 3      | ("4418467"   "5800906"   "5876819").PN. | US-PGPUB; USPAT; USOCR |
| 3 | BRS  | L3  | 15     | ("6004405").URPN.                       | USPAT                  |
| 4 | BRS  | L4  | 101750 | semiconductor and wafer                 | USPAT                  |
| 5 | BRS  | L5  | 1619   | 4 and (bevel or chamfer\$4)             | USPAT                  |
| 6 | BRS  | L6  | 838    | 5 and (ID or mark or marking or groove) | USPAT                  |
| 7 | BRS  | L7  | 65     | 5 and identification                    | USPAT                  |
| 8 | BRS  | L8  | 28     | 5 and label                             | USPAT                  |
| 9 | BRS  | L9  | 778    | 5 and (groove or dot or bar)            | USPAT                  |

|   | Type | L # | Hits   | Search Text                             | DBs   |
|---|------|-----|--------|---|---|
| 1 | BRS  | L1  | 182082 | semiconductor and wafer                 | US-PGPUB; USOCR;<br>EPO; JPO;<br>DERWENT; IBM_TDB |
| 2 | BRS  | L2  | 1937   | 1 and (bevel or chamfer\$4)             | US-PGPUB; USOCR;<br>EPO; JPO;<br>DERWENT; IBM_TDB |
| 3 | BRS  | L4  | 59     | 2 and identification                    | US-PGPUB; USOCR;<br>EPO; JPO;<br>DERWENT; IBM_TDB |
| 4 | BRS  | L5  | 24     | 2 and label                             | US-PGPUB; USOCR;<br>EPO; JPO;<br>DERWENT; IBM_TDB |
| 5 | BRS  | L6  | 599    | 2 and (groove or dot or bar)            | US-PGPUB; USOCR;<br>EPO; JPO;<br>DERWENT; IBM_TDB |
| 6 | BRS  | L3  | 649    | 2 and (ID or mark or marking or groove) | US-PGPUB; USOCR;<br>EPO; JPO;<br>DERWENT; IBM_TDB |